

Title (en)

Electroplating plant, use of electrode and support system therefor and electroplating process

Title (de)

Elektroplattierungsanlage, Verwendung von Elektrode und Gegenhalter dafür und Elektroplattierungsverfahren

Title (fr)

Installation d'électrodéposition, utilisation d'électrode et organe d'appui pour cette installation et procédé d'électrodéposition

Publication

**EP 0922791 B1 20030305 (FR)**

Application

**EP 98402805 A 19981113**

Priority

FR 9715179 A 19971203

Abstract (en)

[origin: US6129820A] An electroplating installation for coating the conducting surface of a part. The installation includes electrodes submerged in a bath. The electrodes rest on a support device that serves as a support and a current supply. The electrodes and the support device form an interface defining a plurality of grooves opening into the bath. The grooves may be formed in the electrodes, in the support device, or in both the electrodes and the support device.

IPC 1-7

**C25D 17/00**; **C25D 7/06**

IPC 8 full level

**C25D 17/10** (2006.01); **C25D 7/06** (2006.01); **C25D 17/00** (2006.01)

CPC (source: EP US)

**C25D 7/0635** (2013.01 - EP US); **C25D 17/005** (2013.01 - EP US); **C25D 17/06** (2013.01 - EP US)

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DOCDB simple family (publication)

**US 6129820 A 20001010**; AT E233835 T1 20030315; DE 69811836 D1 20030410; DE 69811836 T2 20040519; EP 0922791 A1 19990616; EP 0922791 B1 20030305; ES 2192313 T3 20031001; FR 2771757 A1 19990604; FR 2771757 B1 19991231; JP H11229197 A 19990824; US 6334943 B1 20020101

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**US 20454598 A 19981203**; AT 98402805 T 19981113; DE 69811836 T 19981113; EP 98402805 A 19981113; ES 98402805 T 19981113; FR 9715179 A 19971203; JP 34443498 A 19981203; US 63702600 A 20000814